P21547.A01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant

: Nozumi TAKANO et al.

Serial No

: Not Yet Assigned

Filed

: Concurrently Herewith

For

: INCOMBUSTIBLE RESIN COMPOSITION, PREPEG, LAMINATED

PLATE, METAL-CLAD LAMINATED PLATE, PRINTED WIRING

BOARD AND MULTI-LAYER PRINTED WIRING BOARD

PRELIMINARY AMENDMENT

Commissioner of Patents and Trademarks Washington, D.C. 20231

Sir:

Prior to calculation of the filing fees and the examination of the above-identified patent application on the merits, the Examiner is respectfully requested to amend the claims as follows:

IN THE CLAIMS

Please amend claims 15 and 18 as follows (a marked-up copy of the claim amendments is provided as an attachment to this Amendment):

15. (Amended-Clean Text) A printed wiring board prepared by using the laminated plate according to claim 13.